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Document Number / Disk File:	By: Jegan Easwaram	Current Rev: 0A	Date: 11/7/2012
597-786-1180-00 Assemblies Covered:	Jegan Laswarann	UA	11/7/2012
D-1	.000 (786-1180-00)		



Revision	Date	ECO #	Revised By	Description of Changes
0A	11/7/12	E03601	Jegan	Initial Release
			Easwaram	

## **Tools Required:**

- #2 Phillips Screwdriver

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# NOTE: Disconnect any DC Power Cords attached to the power supplies before disassembly of the unit.

Images shown are representative of product and may vary depending on actual configuration.

1.	<ul> <li>Removal of the front bezel (if present) and any labels on the chassis does not require and tools.</li> <li>a. Put the finger in the left side or right side of the bezel, and pull off.</li> <li>b. Peel off any labels on the chassis.</li> <li>c. Discard the bezel and labels into the appropriate Recycle Bin.</li> </ul>	
2.	<ul> <li>Removal of the top access cover requires a #2</li> <li>Phillips screw driver <ul> <li>a. Loosen and remove the screws securing the back cover.</li> <li>b. Press the release buttons on the chassis cover and slide it towards the rear about an inch.</li> <li>c. Loosen and remove the screws securing the top front cover</li> <li>d. Remove access cover and top cover by lifting them up.</li> <li>e. Remove any labels from the chassis and access cover.</li> <li>f. Discard Sheet Metal Cover and Labels into the appropriate Recycle Bin</li> </ul> </li> </ul>	

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3.	<ul> <li>Removal of the HDD and drive tray from chassis requires a security key (provided kit) if locked</li> <li>a. Turn the security screw counter chassis the Unlock symbol</li> <li>b. Press the release button and pull the lever to remove the HDD tray. Refer the other HDD's.</li> </ul>	with ship lock-wise he locking			
4.	<ul> <li>Removal of the HDD from the HDD tray a #2 Phillips screw driver</li> <li>a. Remove the 4 screws securing to the HDD tray and separate from the tray.</li> <li>b. Discard the HDD, HDD tray Screws into the appropriate Bin.</li> </ul>	g the HDD the HDD			
5.	<ul> <li>Removal of the rails (if present) and more ears requires a #2 Phillips screw driver.</li> <li>a. Remove the four screws, two on expull the locking tab and slide the poward front to remove rails.</li> <li>b. Remove the two screws on each of mounting ears.</li> <li>c. Discard the Metal Rails, ears are into the appropriate Recycle Binder Stress and Stress</li></ul>	each side, rails Lo of the two Lo ad Screws	ocking	Tab	

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6.	<ul> <li>Removal of the PCI card and riser card installed) requires a #2 screwdriver.</li> <li>a. Remove three screws securing the card assembly</li> <li>b. Pull the riser card assembly awa chassis</li> <li>c. Remove one screw securing the d. Remove two screw securing the</li> <li>e. Discard the PCI card, riser card Screws into the appropriate R</li> </ul>	he riser ay from the PCI card riser card <b>rd, and</b>		
	Removal of the fan duct does not requitools. a. Remove fan duct from the chas b. Discard the fan duct into the appropriate Recycle Bin			
8.	<ul> <li>Removal of the Motherboard cable cordoes not require any tools.</li> <li>a. Disconnect the front panel cable</li> <li>b. Disconnect the fan connectors.</li> <li>c. Disconnect the drive cable.</li> <li>d. Disconnect the USB cable conn</li> <li>e. Disconnect the power cables from mother board.</li> </ul>	e. ector.		

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9.	<ul> <li>Removal of the fans does not require any a. Remove the fan assemble pulling edge in the direction of the arrow b. Lift up the fan assembly from the c. Discard the fans into the appropression Recycle Bin.</li> </ul>	the rear chassis		2		
10.	<ul> <li>Removal of the HDD backplane requires</li> <li>Phillips screw driver. Removal of the baccable connections does not require any to</li> <li>a. Unplug all drive cables Discompower cables from the power</li> <li>b. Unplug SGPIO cable.</li> <li>c. Loosen an remove the screws the backplane as illustration at show.</li> <li>d. Discard the Cables, backpla screws into the appropriate Bin.</li> </ul>	ckplane ools. nnect the supply. securing rrow <b>ne, and</b>	é			

11.	Removal of the Heat Sink requires a #2 Phillips	
	screw driver.	
	a. Unscrew each of the 4 screws on the corners of the heat sink.	
	b. Pull the Heat Sink upwards to remove it, exposing the CPU.	
	c. Discard the Heat Sink into the appropriate Recycle Bin.	
		<u>e</u>

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12.	<ul> <li>Removal of the CPU(s) does not re Perform the steps 4, 3, 2, 1 and opp pointing arrows <ul> <li>a. Lift the CPU latch out and u the CPU.</li> <li>b. Carefully pick up the CPU of and lift it off the board.</li> <li>c. Discard the CPU into the a Recycle Bin</li> </ul> </li> </ul>	oosite of the up to unfasten on both sides		
15.	<ul> <li>Removal of the Memory DIMMs from motherboard does not require any to a. Remove each of the Memory opening the two latches, one the DIMM connector. Lift mestraight out to remove.</li> <li>b. Discard the Memory DIMM appropriate Recycle Bin.</li> </ul>	ools. y DIMMs by on each end of nemory DIMM		
16.	Removal of Lithium Battery from t         does not require any tools.         a. Remove the coin style         Battery.         b. Discard the Lithium         the appropriate Rec	e Lithium 1 <b>Battery into</b>		
	*** CAUTION *** Care should be observed when di battery to avoid shorting it!	¢		

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17.	<ul> <li>Removal of the power supplies does not any tools.</li> <li>a. Press the retaining clip on the rithe power supply and pull the power supply and pull the power supply and pull the power supply (s) in appropriate Recycle Bin</li> </ul>	ght side of ower supply		
18.	Removal of the PDB cage requires a # screw driver. a. Remove six screws securing the to the chassis b. Remove the PDB cage from the	e PDB cage		

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19	<ul> <li>Removal of the PDB cage and PDB requiphillips screw driver.</li> <li>a. Remove five screws from the cage, one screw on top and two on both sides</li> <li>b. Remove three screws securing to the cage</li> <li>c. Remove the PDB</li> <li>d. Discard the PDB cage, PDE screws into the appropriate Bin</li> </ul>	e PDB wo screws g the PDB				
18.	<ul> <li>Removal of the motherboard requires a screw driver.</li> <li>a. Ensure that all cables and connect motherboard have been removed.</li> <li>b. Remove the 12 screws from the motherboard.</li> <li>c. Remove the motherboard by slidit towards the front of the unit to dia from the rear panel, and then lift motherboard up and out.</li> <li>d. Discard the Motherboard and sinto the appropriate Recycle Bit</li> </ul>	tors to the ng it sengage it the crews				

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9.	Removal of the Front Panel requires a #2	2				

Phillips screw driver.
a. Disconnect the front panel cables
b. Remove the screws holding the Front Panel to the front of the unit.
c. Pull the Front Panel out of the unit.
d. Discard the Front Panel, cables and Screws into the appropriate Recycle Bin.

### DISCARD THE FULLY DISASSEMBLED UNIT IN THE APPROPRIATE RECYCLE BIN.

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#### D-1000 (786-1180-00)

Recycling/Material Code	Important Information	
Material /Components, which must be removed and treated separately		
Lithium Battery	Battery free of hazardous substances, installed	
	in socket on the motherboard	
Printed circuit boards	Motherboard, DIMMs, PCI card, PCI riser,	
	Power Supply, Front Panel	
Drives	Hard Drives and DVD ROM	
Material /Components, which can disturb certain recycling processes		
Aluminum	Heat Sink, Mounting Ears	
Material /Components, through which benefit	ts can normally be achieved	
Cold Rolled Steel	Access cover, chassis bottom, chassis rear	
	panel, Bezel	
* ABS	Pushbuttons, Air Shroud	
Cables	Distributed in device, & power cord	
Other	Blowers	
Special notes		
* Flame retardant of plastics <b>do not</b> contain PBB and PBDE.		

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## D-1000 (786-1180-00)

## Annex A

Producer:	<company addressing="" name,="" on="" other="" producer="" the=""></company>
Scope of information sheet:	< product category as in Annex IA of WEEE Directive, or type of equipment as in Annex 1B of WEEE Directive, or producer's Product Family, or single products identified by brand and model name >

Component or Material	Remarks / Location
Battery (internal *) containing Mercury (Hg)/ NiCad/Lithium/	Lithium battery 🗸
Other	located on the motherboard
Backlighting lamps of LCD/TFT or similar screens containing Mercury (Hg)	NONE
Mercury (Hg) in other applications**	NONE
Cadmium**	NONE
Gas discharge lamps	NONE
Plastic containing brominated flame retardants other than in Printed Circuit Assemblies ***	NONE
Liquid Crystal Displays with a surface greater than 100 cm2	NONE
Capacitors with PCB's	NONE
Capacitors with substances of concern**** + height > 25 mm, diameter > 25 mm or proportionately similar volume	NONE
Asbestos	NONE
Refractory ceramic fibres	NONE
Radio-active substances	NONE
Beryllium Oxide	NONE
Other forms of Beryllium	BE-CU in some connector contacts
Gasses - which fall under Regulation (EC) 2037/2000 and all hydrocarbons (HC).	NONE
Components with pressurised gas which need special attention (Pressure > 1,5 bar) ****	NONE
Liquids ***** if volume > 10 cl (or equivalence in weight, e.g. for PCB, oil)	NONE
Mechanical components that store mechanical energy (i.e. springs) or equivalent parts which need special attention ***** (diameter > 10 mm and height > 25 mm or proportionally	NONE
similar volume and expanding)	
PBDE (deca- & octa-BDE) and Perfluorocatane sulfantes (PFOS) in Directive 2006/122/EC	NONE

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= arrow indicates the need for the location of the compartment/ substances within the product. When the location of a substance/ components is requested, it is at part level, e.g. main board, housing etc

\* Internal means that batteries can only be removed by opening the product by means of (a) tool(s).

\*\* Substances are considered to be in the product if present above the levels specified in Commission Decision 2005/618/EC related to Directive 2002/95/(EC) (RoHS Directive) or if their use is permitted through exemptions in the Annex of Directive 2002/95(EC)

\*\*\* To be coherent with industry current standards and practices on tracking of plastic parts, Directive 2002/96 (EC) Annex II requirement is understood to focus on plastic parts that weight more than 25 g.

\*\*\*\* Substance of concern other than PCB, to be specified/ addressed further in the context of Directive 2002/96 (EC) Annex II national requirements and European developments

\*\*\*\* Needs of equivalent nature as those for maintenance, service manuals and installation for safety purposes.